

SPECIFICATION

PART NO. : MT6224-AHRG-A

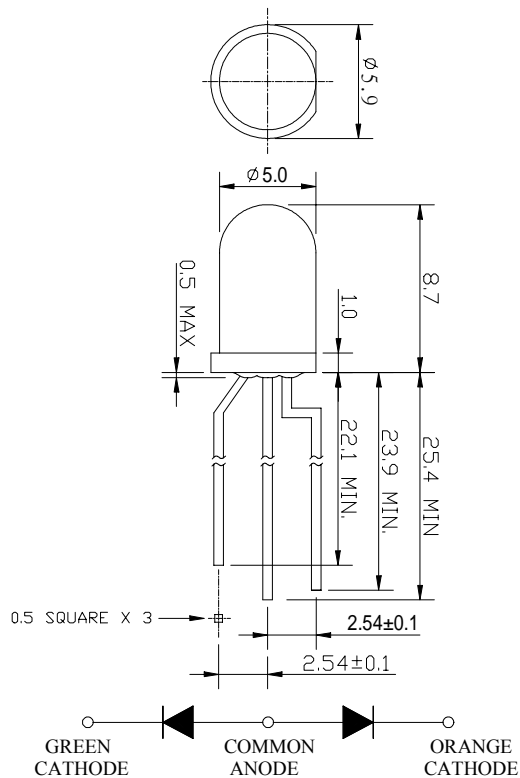
5.0mm ROUND BI-COLOR LAMP (2 LEADS)



ATTENTION
OBSERVE PRECAUTION
FOR HANDLING
ELECTRO STATIC
SENSITIVE
DEVICES

Description

This G/R lamp is made with AlGaAs/GaAs red chip and GaP/GaP green chip and white diffused epoxy resin.



Notes:

1. ALL DIMENSIONS ARE IN mm.
2. TOLERANCE IS $\pm 0.25\text{mm}$ UNLESS OTHERWISE NOTED.

Description

Part No.	LED Chip		Description
	Material	Emitting Color	
MT6224-AHRG-A	GaP/GaP	Green	White diffused
	AlGaAs/GaAs	Red	

Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Rating	Unit
Power Dissipation	P _d	78	mW
Reverse Voltage	V _R	5	V
D.C. Forward Current	I _f	30	mA
Reverse (Leakage) Current	I _r	100	μ A
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-25 to +85	
Storage Temperature Range	T _{stg.}	-40 to +100	
Lead Soldering Temp.(1.6mm from body) for 5 seconds		260	

Electrical and Optical Characteristics:
GREEN

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =10mA	30.0	50.0		mcd
Forward Voltage	V _f	I _f =10mA		2.1	2.6	V
Peak Wavelength	λ _P	I _f =10mA		568		nm
Dominant Wavelength	λ _D	I _f =10mA		570		nm
Reverse (Leakage) Current	I _r	V _r =5V			100	μA
Viewing Angle	2 1/2	I _f =10mA		70		deg
Spectrum Line Halfwidth	Δλ	I _f =10mA		30		nm

NOTE: THE DATAS TESTED BY IS TESTER

Absolute Maximum Ratings at Ta=25

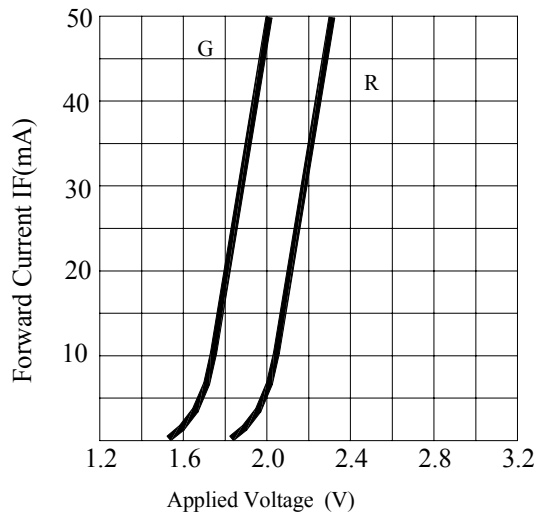
Parameter	Symbol	Rating	Unit
Power Dissipation	P _d	66	mW
Reverse Voltage	V _R	5	V
D.C. Forward Current	I _f	30	mA
Reverse (Leakage) Current	I _r	100	μ A
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-25 to +85	
Storage Temperature Range	T _{stg.}	-40 to +100	
Lead Soldering Temp.(1.6mm from body) for 5 seconds		260	

Electrical and Optical Characteristics:
RED

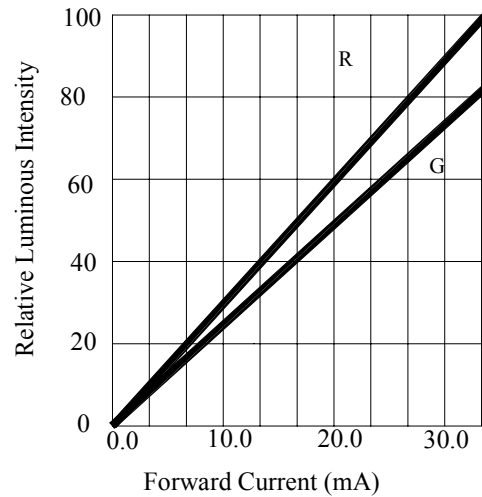
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =10mA	36.0	60.0		mcd
Forward Voltage	V _f	I _f =10mA		1.8	2.2	V
Peak Wavelength	λ _P	I _f =10mA		630		nm
Dominant Wavelength	λ _D	I _f =10mA		622		nm
Reverse (Leakage) Current	I _r	V _r =5V			100	μA
Viewing Angle	2 1/2	I _f =10mA		70		deg
Spectrum Line Halfwidth	Δλ	I _f =10mA		20		nm

NOTE: THE DATAS TESTED BY IS TESTER

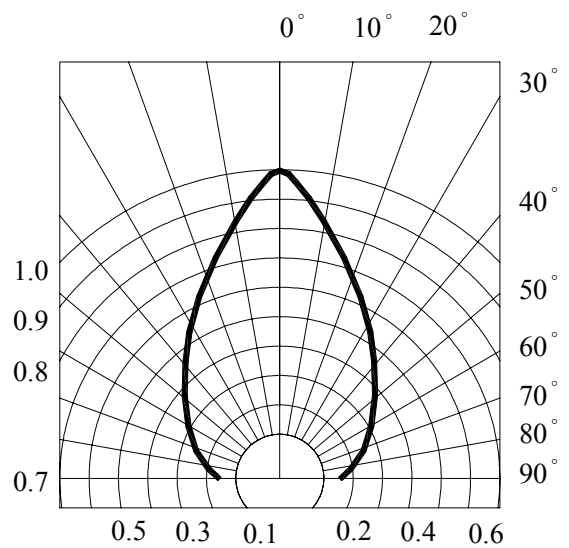
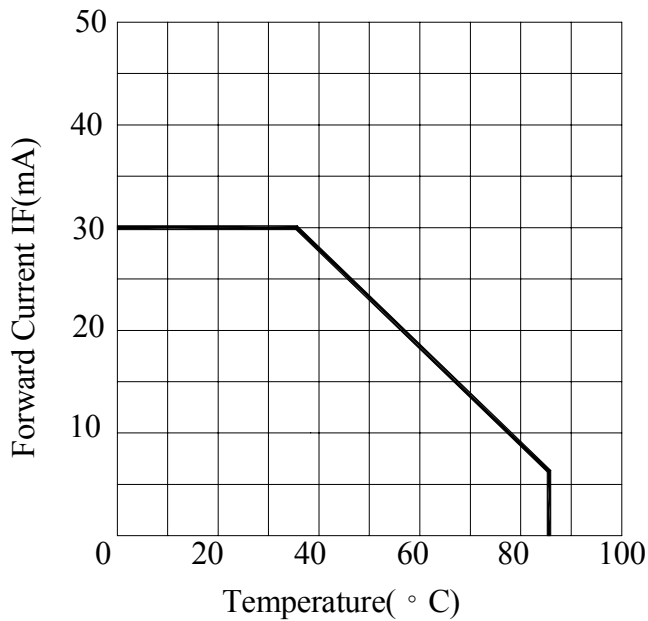
Typical Electrical / Optical Characteristics Curves :



FORWARD CURRENT VS. APPLIED VOLTAGE



FORWARD CURRENT VS. LUMINOUS INTENSITY



RADIATION DIAGRAM

Precautions:

TAKE NOTE OF THE FOLLOWING IN USE OF LED

1. Temperature in use

Since the light generated inside the LED needs to be emitted to outside efficiently, a resin with high light transparency is used; therefore, additives to improve the heat resistance or moisture resistance (silica gel, etc) which are used for semiconductor products such as transistors cannot be added to the resin.

Consequently, the heat resistant ability of the resin used for LED is usually low; therefore, please be careful on the following during use.

Avoid applying external force, stress, and excessive vibration to the resins and terminals at high temperature. The glass transition temperature of epoxy resin used for the LED is approximately 120-130 .

At a temperature exceeding this limit, the coefficient of linear expansion of the resin doubles or more compared to that at normal temperature and the resin is softened.

If external force or stress is applied at that time, it may cause a wire rupture.

2. Soldering

Please be careful on the following at soldering.

After soldering, avoid applying external force, stress, and excessive vibration until the products go to cooling process (normal temperature), <Same for products with terminal leads>

(1) Soldering measurements:

Distance between melted solder side to bottom of resin shall be 1.6mm or longer.

(2) Solder dip: Preheat: 90 max. (Backside of PCB), Within 120 seconds

Solder bath: 250 max. (Solder temperature), Within 5 seconds

(3) Soldering iron : 250 max. (Temperature of soldering iron tip), Within 3 seconds

3. Insertion

Pitch of the LED leads and pitch of mounting holes need to be same

4. Others

Since the heat resistant ability of the LED resin is low, SMD components are used on the same PCB, please mount the LED after adhesive baking process for SMD components. In case adhesive baking is done after LED lamp insertion due to a production process reason, make sure not to apply external force, stress, and excessive vibration to the LED and follow the conditions below.

Baking temperature: 120 max. Baking time: Within 60 seconds

If soldering is done sequentially after the adhesive baking, please perform the soldering after cooling down the LED to normal temperature.